

Advanced Packaging Update: Market and Technology Trends

Vol. 4-0715

The fourth volume of the Advanced Packaging Update features special coverage of the BGA and CSP markets with a five-year forecast by package construction. The CSP market is divided into laminate, flex circuit, and leadframe (QFN) substrates. Market forecasts for stacked die CSPs and package-on-package (PoP) are also provided. Estimates of the market for each package type are based on input from captive as well as merchant assembly operations. Key applications and drivers for unit volume growth are highlighted. A special section is devoted to the latest developments in singulation for thin die.

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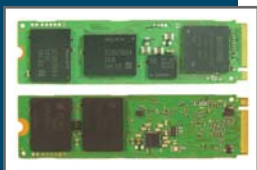
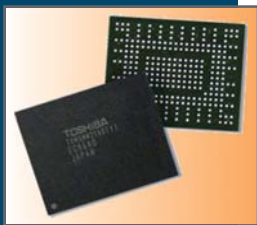
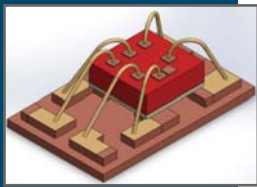
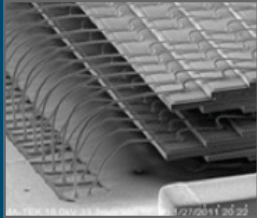
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